





ZXMN10A07Z

100V N-CHANNEL ENHANCEMENT MODE MOSFET IN SOT89 PACKAGE

Product Summary

V _{(BR)DSS}	R _{DS(on)} Max	I _D max T _A = 25°C (Note 6)
100V	700m $Ω$ @ V _{GS} = 10 V	1.4A
1007	900m Ω @ V _{GS} = 6V	1.2A

Description and Applications

This MOSFET has been designed to minimize the on-state resistance $(R_{DS(on)})$ and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- DC-DC Converters
- · Power Management functions
- Motor control
- Disconnect switches

Features and Benefits

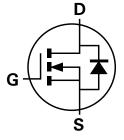
- Low On-Resistance
- Low Threshold
- Fast Switching Speed
- Low Gate Drive
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

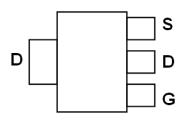
- Case: SOT89
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish
- Weight: 0.052 grams (approximate)



Top View



Device symbol



Top View Pin-Out

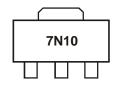
Ordering Information (Note 4)

ĺ	Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
	ZXMN10A07ZTA	7N10	7	12	1,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen and Antimony free, "Green" and Lead-Free.
- 3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com

Marking Information



7N10 = Product type Marking Code

ZXMN10A07Z

Maximum Ratings @TA = 25°C unless otherwise specified

Characteristic Drain-Source Voltage			Symbol	Value 100	Unit V
			V _{DSS}		
Gate-Source Voltage			V _{GSS}	±20	V
Continuous Drain Current	Steady State	@ V _{GS} = 10V; T _A = 25°C (Note 6) @ V _{GS} = 10V; T _A = 70°C (Note 6) @ V _{GS} = 10V; T _A = 25°C (Note 5)	ID	1.4 1.1 1.0	А
Pulsed Drain Current (Note 7)			I _{DM}	4.2	Α
Continuous Source Current (Body Diode) (Note 6)			I _S	2.1	Α
Pulsed Source Current (Body Diode) (Note 7)		I _{SM}	4.2	А	

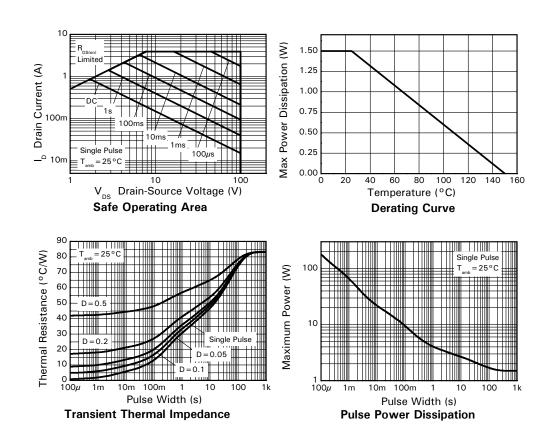
Thermal Characteristics @TA = 25°C unless otherwise specified

Characteristic		Value	Unit
Power Dissipation (Note 5)	D-	1.5	W
Linear Derating Factor	P _D	12	mW/°C
Power Dissipation (Note 6)	ם	2.6	W
Linear Derating Factor	P _D	21	mW/°C
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	83.3	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	R _{θJA}	47.4	°C/W
Thermal Resistance, Junction to Leads (Note 8)	$R_{ heta JL}$	6.36	°C/W
Operating and Storage Temperature Range	T_{J} , T_{STG}	-55 to +150	°C

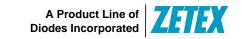
Notes: 5. For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.

- 6. For a device surface mounted on FR4 PCB measured at $t \le 10$ sec.
- 7. Repetitive rating 25mm x 25mm FR4 PCB, D = 0.02, pulse width 300µs pulse width limited by maximum junction temperature.
- 8. Thermal resistance from junction to solder-point (at the end of the drain lead).

Thermal Characteristics







ZXMN10A07Z

Electrical Characteristics @TA = 25°C unless otherwise specified

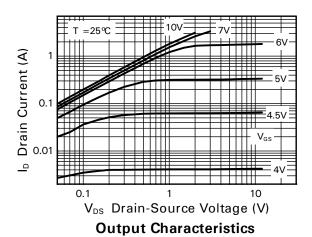
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage	BV _{DSS}	100	-	-	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current T _J = 25°C	I _{DSS}	-	-	1.0	μΑ	$V_{DS} = 100V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	-	-	100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS							
Gate Threshold Voltage	V _{GS(th)}	2	-	4	٧	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance (Note 9)		N) -	-	700	mΩ	$V_{GS} = 10V, I_D = 1.5A$	
Static Drain-Source On-Resistance (Note 9)	R _{DS (ON)}		-	900		$V_{GS} = 6V, I_{D} = 1A$	
Forward Transconductance (Note 9 & 11)	g _{FS}	-	1.6	-	S	$V_{DS} = 15V, I_{D} = 1A$	
Diodes Forward Voltage (Note 9)	V_{SD}	-	0.85	0.95	V	$T_J = 25^{\circ}C$, $I_S = 1.5A$, $V_{GS} = 0V$	
DYNAMIC CHARACTERISTICS							
Input Capacitance (Note 10 & 11)	C _{iss}	-	138	-	pF	., 50,4,3,4	
Output Capacitance (Note 10 & 11)	Coss	-	12	-	рF	$V_{DS} = 50V, V_{GS} = 0V,$ -f = 1.0MHz	
Reverse Transfer Capacitance (Note 10 & 11)	C _{rss}	-	6	-	pF	71 = 1.0IVIH2	
Gate Resistance (Note 10 & 11)	Rg	1.8	-	2.6	Ω	$f = 1MHz$, $V_{GS} = 0V$, $V_{DS} = 0V$	
Total Gate Charge (Note 10 & 11)	Qq	-	2.9	-	nC		
Gate-Source Charge (Note 10 & 11)	Q _{gs}	-	0.7	-	nC	$V_{GS} = 10V, V_{DS} = 50V,$	
Gate-Drain Charge (Note 10 & 11)	Q_{gd}	-	1	-	nC	$I_D = 1A$	
Reverse Recovery Time (Note 11)	t _{rr}		27		ns	$T_J = 25^{\circ}C, I_F = 1A,$	
Reverse Recovery Charge (Note 11)	Q _{rr}		12		nC	di/dt = 100A/μs	
Turn-On Delay Time (Note 10 & 11)	t _{D(on)}	-	1.8	-	ns		
Turn-On Rise Time (Note 10 & 11)	t _r	-	1.5	-	ns	$V_{GS} = 10V, V_{DD} = 50V,$	
Turn-Off Delay Time (Note 10 & 11)	t _{D(off)}	-	4.1	-	- ns $R_G = 6\Omega$, $I_D = 1A$		
Turn-Off Fall Time (Note 10 & 11)	t _f	-	2.1	-	ns		

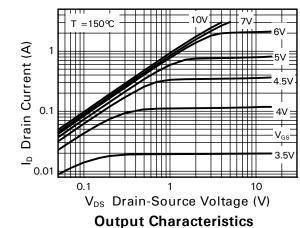
Notes:

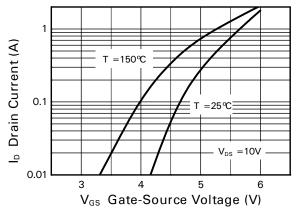
^{9.} Measured under pulsed conditions. Pulse width $\leq 300 \mu s$; duty cycle $\leq 2\%$. 10. Switching characteristics are independent of operating junction temperature. 11. For design aid only, not subject to production testing.



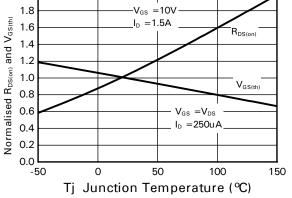
Typical Characteristics



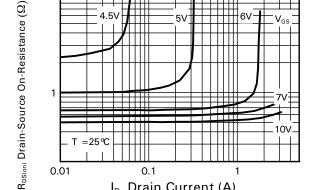




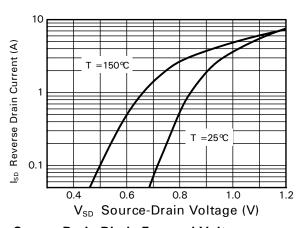
2.0



Typical Transfer Characteristics



Normalised Curves v Temperature



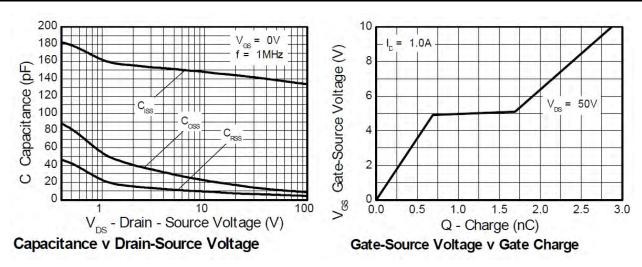
On-Resistance v Drain Current

ID Drain Current (A)

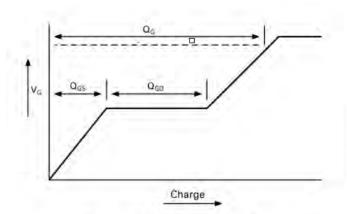
Source-Drain Diode Forward Voltage



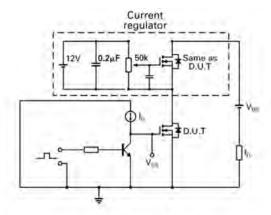
Typical Characteristics - Continued



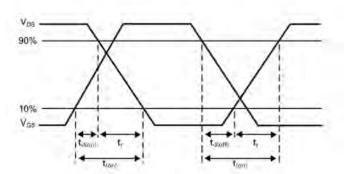
Test Circuits



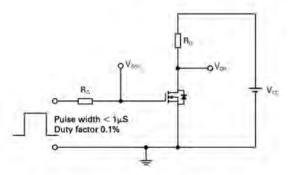
Basic gate charge waveform



Gate charge test circuit



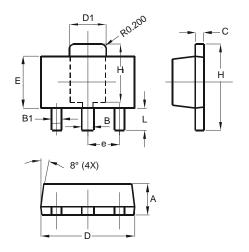
Switching time waveforms



Switching time test circuit

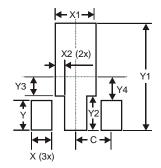


Package Outline Dimensions



SOT89				
Dim	Min	Max		
Α	1.40	1.60		
В	0.44	0.62		
B1	0.35	0.54		
C	0.35 0.44			
D	4.40	4.60		
D1	1.62	1.83		
Е	2.29	2.60		
е	1.50 Typ			
Н	3.94	4.25		
H1	2.63	2.93		
L	0.89	1.20		
All Dimensions in mm				

Suggested Pad Layout



Dimensions	Value (in mm)
X	0.900
X1	1.733
X2	0.416
Υ	1.300
Y1	4.600
Y2	1.475
Y3	0.950
Y4	1.125
С	1.500





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